Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2909	(29/832).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR ·	OFF	2007/03/22 16:05
L2	121279	"439"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 16:05
L3	910	L2 and (sink spreader) and ((integrated adj circuit) die chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 16:05
L4	820	L3 and (substrate board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 16:05
L5	3209	L2 and (emi (electromagnetic adj interference))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 16:05
L6	82	L5 and (sink spreader) and ((integrated adj circuit) die chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	OFF	2007/03/22 16:05
L7	3245	L2 and (emi (faraday adj cage) (electromagnetic adj interference))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 16:05
L8	84	L7 and (sink spreader) and ((integrated adj circuit) die chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 16:05

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L9	2528	(361/760,762,764).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 16:05
L10	1993	(257/777).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 16:05
L11	819	(L9 L1 L10) and (sink spreader) and ((integrated adj circuit) die chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 16:05
L12	794	L11 and (substrate board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	OFF	2007/03/22 16:05
L13	3017	(361/704).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 16:05
L14	1262	L13 and (sink spreader) and ((integrated adj circuit) die chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 16:05
L15	109	L14 and (emi (faraday adj cage) (electromagnetic adj interference))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 16:05
L16	3017	(361/704).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 16:05

L17	1262	L16 and (sink spreader) and	US-PGPUB;	OR	OFF	2007/03/22 16:05
		((integrated adj circuit) die chip)	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB			
L18	2528	(361/760,762,764).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 16:05
L19	109	L17 and (emi (faraday adj cage) (electromagnetic adj interference))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 17:48
L20	121279	"439"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 16:05
L21	32 4 5	L20 and (emi (faraday adj cage) (electromagnetic adj interference))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 16:05
L22.		L21 and (sink spreader) and ((integrated adj circuit) die chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 16:05
L23	2909	(29/832).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 16:05
L24 ·	910	L20 and (sink spreader) and ((integrated adj circuit) die chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 16:05

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L25	3209	L20 and (emi (electromagnetic adj interference))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 17:52
L26	82	L25 and (sink spreader) and ((integrated adj circuit) die chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 17:51
L27	2	("20030174478").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 16:05
L28	1993	(257/777).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 16:05
L29	819	(L18 L23 L28) and (sink spreader) and ((integrated adj circuit) die chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 16:05
L30 .	794	L29 and (substrate board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	OFF	2007/03/22 16:05
L31	820	L24 and (substrate board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 16:05
L32	6289	((361/717-719) or (257/706,707, 713,721,722)).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 17:49

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L34	5294	32 and @ad<"20040303"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 17:51
L35	2522	34 and (sink spreader) and ((integrated adj circuit) die chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/22 17:51
L36	136	35 and (emi (electromagnetic adj interference))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	OFF	2007/03/22 18:33
L37	579	((361/719,718,764) or (257/707, 713)).CCLS.	US-PGPUB	OR	OFF	2007/03/22 18:34
L38	116	((substrate board) and (chip (integrated adj circuit) die) and (sink heatsink (cold adj plate)) and (ground emi shield)).clm.	US-PGPUB	OR	OFF	2007/03/22 18:36
S1	2454	(361/760,762,764).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/04 13:49
S2	2761	(29/832).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/04 13:49
S3	1837	(257/777).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/04 13:49
S4	117902	"439"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/04 13:50

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S5	858	S4 and (sink spreader) and ((integrated adj circuit) die chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	OFF	2006/08/04 13:53
S6	771	S5 and (substrate board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/04 13:51
S7	771	(S1 S2 S3) and (sink spreader) and ((integrated adj circuit) die chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/04 13:51
S8	747	S7 and (substrate board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/04 13:52
S9	2965	S4 and (emi (electromagnetic adj interference))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/04 13:54
S10	75	S9 and (sink spreader) and ((integrated adj circuit) die chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/04 13:54
S11	. 2997	S4 and (emi (faraday adj cage) (electromagnetic adj interference))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/04 13:55
S12	77	S11 and (sink spreader) and ((integrated adj circuit) die chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/04 13:55

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S13	2801	(361/704).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/04 13:55
S14	1186	S13 and (sink spreader) and ((integrated adj circuit) die chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/04 13:55
S15	102	S14 and (emi (faraday adj cage) (electromagnetic adj interference))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF ,	2006/08/04 13:55
S16	2	("20030174478").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/04 12:44
S17	2858	(29/832).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/04 14:48
S18	120087	"439"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/04 14:48
S19	887	S18 and (sink spreader) and ((integrated adj circuit) die chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/04 14:48
S20	799	S19 and (substrate board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/04 14:48

S21	3126	S18 and (emi (electromagnetic adj interference))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/04 14:48
S22	80	S21 and (sink spreader) and ((integrated adj circuit) die chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/04 14:48
S23	3160	S18 and (emi (faraday adj cage) (electromagnetic adj interference))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/04 14:48
S24	82	S23 and (sink spreader) and ((integrated adj circuit) die chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/04 14:48
S25	2498	(361/760,762,764).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/04 14:48
S26	1941	(257/777).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR [*]	OFF	2007/01/04 14:48
S27	803	(S25 S17 S26) and (sink spreader) and ((integrated adj circuit) die chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/04 14:48
S28	779	S27 and (substrate board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/04 14:48

S29	2944	(361/704).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/04 14:48
S30	1235	S29 and (sink spreader) and ((integrated adj circuit) die chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	OFF	2007/01/04 14:48
S31	106	S30 and (emi (faraday adj cage) (electromagnetic adj interference))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/04 14:48